15. A transfer film according to claim 1, wherein the sacrificial material is present in each electrical protolayer in a range from 25 to 95 wt%.

16. A transfer film according to claim 1, wherein the electrical protolayer stack comprises at least 10 electrical protolayers.

17. A transfer film according to claim 1, wherein at least selected electrical protolayers comprise inorganic nanoparticles and an organometallic polymer or coordination compound.

18. A method, comprising:

laminating the transfer film according to claim 1 to a receptor substrate; and

baking out sacrificial material to form an electrical stack.

19. A method according to claim 18, wherein the baking out step forms at least one porous layer and further comprising infusing the porous layer with an electrically active liquid.

20. A method according to claim 19, wherein the electrically active liquid comprises an electrolyte, an electrochromic dye, a liquid crystal, an ionic species or a ferrofluid.

21. A method according to claim 18, wherein the receptor substrate comprises glass, quartz or sapphire.

~~22. A method according to claim 18, wherein the receptor substrate comprises an electrically conductive layer.~~

~~23. A method according to claim 18, wherein the electrical stack forms at least a portion of an electrochromic device.~~

~~24. A method according to claim 18, wherein the electrical stack forms at least a portion of a battery.~~

~~25. A method according to claim 18, wherein the electrical stack forms at least a portion of a capacitor.~~

~~26. A method according to any of claims 18, wherein the receptor substrate comprises a bottom electrode.~~

~~27. A method according to any of claims 18 further comprising applying a top electrode on the electrical stack.~~

~~28~~22. A method of forming a transfer film, comprising:

forming a plurality of electrical protolayers to form an electrical protolayer stack, each protolayer independently comprising a sacrificial material and a thermally stable material and having a uniform thickness of less than 25 micrometers.

~~29~~23. A method according to claim ~~28~~22, wherein the electrical protolayers are interdigitated.

~~30~~24. A method according to claim ~~28~~22, wherein forming a plurality of electrical protolayers comprises coextruding the plurality of electrical protolayers.

~~31~~25. A method according to claim ~~28~~22, wherein each electrical protolayer of the electrical protolayer stack independently exhibits a complex viscosity of between 10^3 and 10^4 Poise at a shear rate of 100/s when heated to a temperature between its T_g and T_{dec}.

~~32. A method according to any of claims 28, wherein the electrical protolayer stack is formed on a releasable surface of a polymeric support substrate.~~